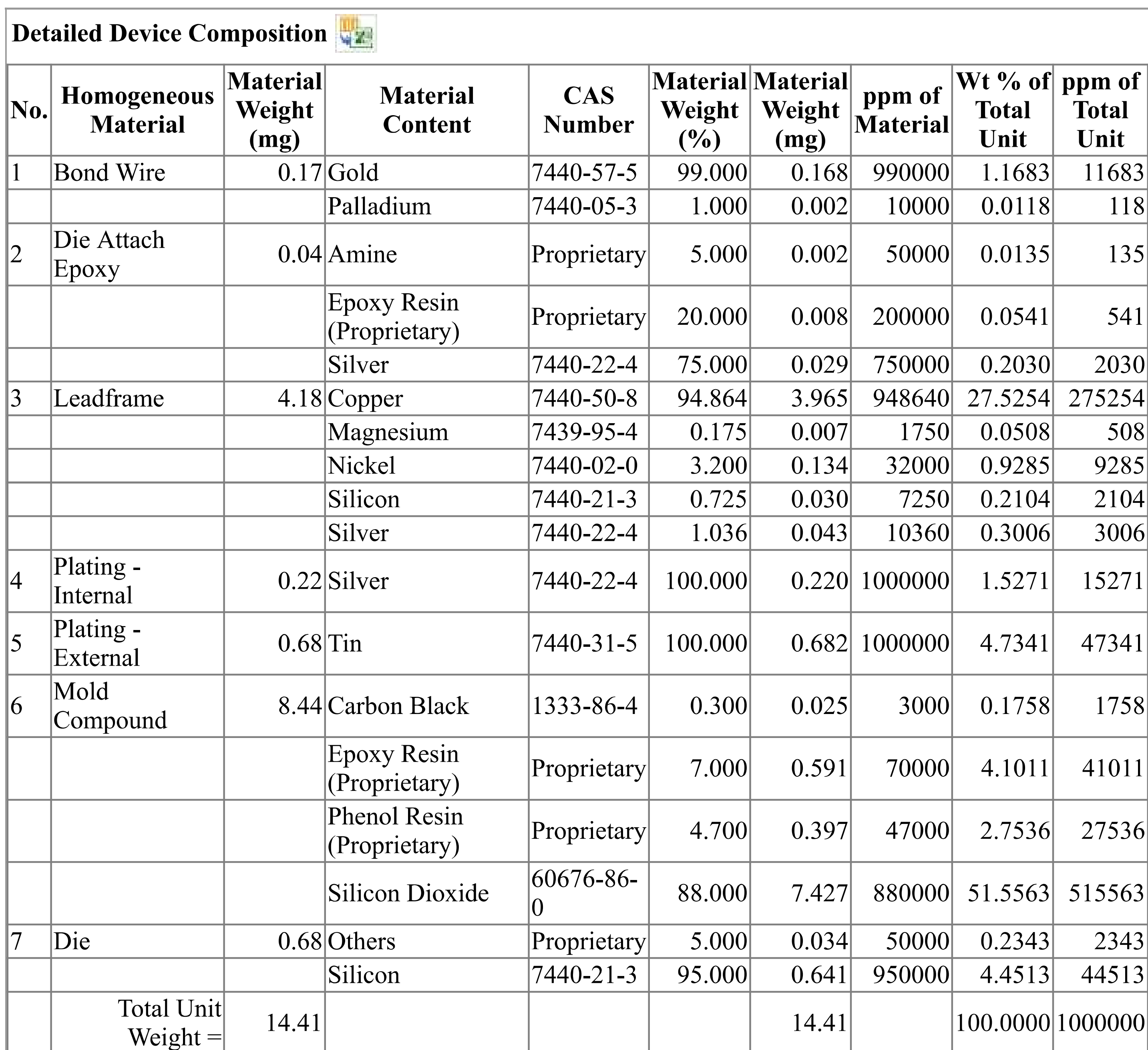
Date: 4/20/2021
Material Number: SI7215-B-00-IV
Pkg Config.: PK1408



Detailed Device Composition

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Bond Wire	0.17	Gold	7440-57-5	99.000	0.168	990000	1.1683	11683
			Palladium	7440-05-3	1.000	0.002	10000	0.0118	118
2	Die Attach Epoxy	0.04	Amine	Proprietary	5.000	0.002	50000	0.0135	135
			Epoxy Resin (Proprietary)	Proprietary	20.000	0.008	200000	0.0541	541
			Silver	7440-22-4	75.000	0.029	750000	0.2030	2030
3	Leadframe	4.18	Copper	7440-50-8	94.864	3.965	948640	27.5254	275254
			Magnesium	7439-95-4	0.175	0.007	1750	0.0508	508
			Nickel	7440-02-0	3.200	0.134	32000	0.9285	9285
			Silicon	7440-21-3	0.725	0.030	7250	0.2104	2104
			Silver	7440-22-4	1.036	0.043	10360	0.3006	3006
4	Plating - Internal	0.22	Silver	7440-22-4	100.000	0.220	1000000	1.5271	15271
5	Plating - External	0.68	Tin	7440-31-5	100.000	0.682	1000000	4.7341	47341
6	Mold Compound	8.44	Carbon Black	1333-86-4	0.300	0.025	3000	0.1758	1758
			Epoxy Resin (Proprietary)	Proprietary	7.000	0.591	70000	4.1011	41011
			Phenol Resin (Proprietary)	Proprietary	4.700	0.397	47000	2.7536	27536
			Silicon Dioxide	60676-86-0	88.000	7.427	880000	51.5563	515563
7	Die	0.68	Others	Proprietary	5.000	0.034	50000	0.2343	2343
			Silicon	7440-21-3	95.000	0.641	950000	4.4513	44513
	Total Unit Weight =	14.41				14.41		100.0000	1000000